



Complex Assembly Solutions

i3 Electronics: Assembly Solutions that Exceed Your Expectations

i3 Electronics merges engineering, manufacturing, product reliability and life cycle support into assembly solutions that exceed both your expectations and industry standards.

The power of our solutions lies in the ability to provide you with a breadth of products and services all under one roof. We can build your prototypes, design a process to address a new technology, handle your assembly challenges, and then develop and execute in circuit or functional tests.

Through the broad depth of our knowledge and experience, we will help you reduce your product development time and boost your profitability during each product life cycle phase.

We will help you launch your product domestically, and then boost your profitability during volume production

We deliver a unique mix of leading edge technology and technical expertise that gives you a time to market advantage and competitive differentiation.

And our capability and reliability meets the need of these industries:

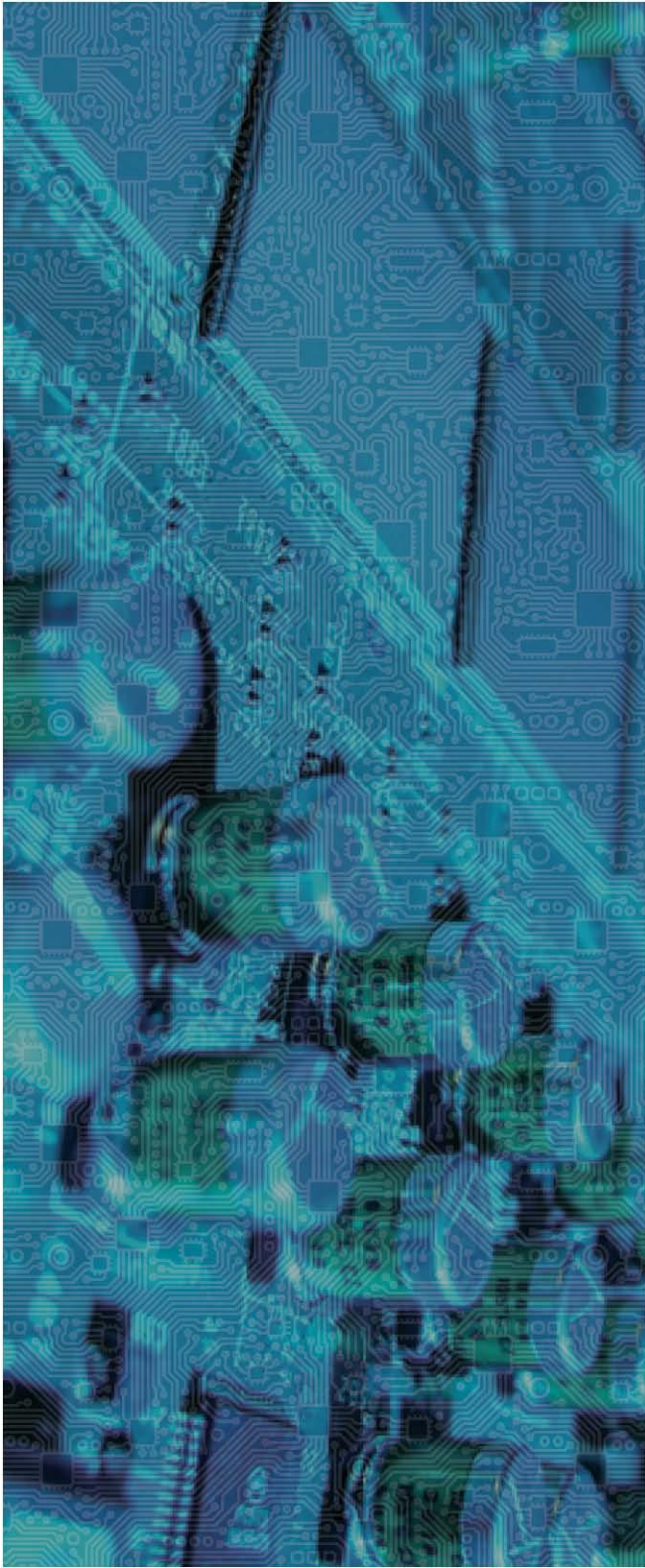
- IT, Servers and Super Computing
- Aerospace and Defense
- Homeland Security and Government
- Industrial
- Medical
- Automated Test Equipment

FEATURES

- Exceptional service delivered on time - 99 percent or better
- A wide range of products - from high end, complex mission critical assemblies to simpler support PCB assemblies
- Full hybrid assembly, backplane, chassis and system build
- Focused NPI to production launch, with support from dedicated program managers and engineers

QUALITY & PROCESS CONTROLS:

- Traceable systems and documentation through each product's manufacture
- Comprehensive process capabilities, including stencil design, automated solder inspection, AOI/X-ray examination, cleaning, rework/repair and high reliability testing
- Extensive testing, including FHP, ICT and FCT using both industry standard and EI developed protocols and equipment
- Top line assembly process development, including RoHS conversion and optimization
- Flexible, competitive supply chain management
- Unequaled life cycle support, including analysis, repair and upgrade, testing and more



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MAXIMUM ASSEMBLY SIZE

38" x 36" (96.5 cm x 91.4 cm) for SMT 18" x 24" (457 mm x 610 mm) for SMT
36" x 48" (91.4 cm x 122 cm) 18" x 24" (457 mm x 610 mm) for for
non-SMT backplanes non-SMT backplanes 0.35" (0.9 cm) thickness

TECHNOLOGY

SMT SMT Press fit Press fit Wave solder and selective Wave
solder and selective

PTH solder PTH solder Hand assembly and solder Hand
assembly and solder LGA

COMPONENTS

BGA/CGA down to 0.04" (1.0mm)
uBGA and CSP down to .5 mm pitch
DCA wire bond and flip chip
Perimeter lead fine pitch to 0.01" (0.25 mm)
LGA Pitch down to 0.04" (1.0 mm)
BGA/CGA down to 0.03" (0.8 mm) pitch

CORE PRODUCT

Very thick PCBs; high-density hybrid assemblies (average components >1500);
double-sided, large complex boards with mixed technology

Hybrid assemblies (SMT/PTH/Press Fit)

Components: high I/O area array modules (CGA, LGA, PBGA)

Connectors: dense, high I/O connectors

Mechanical: cage, chassis, system assemblies

High density BGA/area array rework

TESTING

Teredyne 2286, 2287LX

Ultraprobe

Scorpion Flying Probe

Functional system level

ESS and burn-in

CERTIFICATIONS

AS 9100

ISO 9001

ISO 13485

ISO 14001

IPC-A-610

JSTD 001